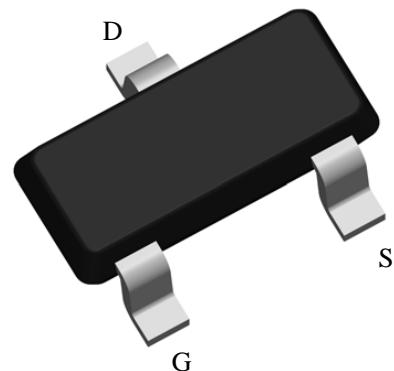


## **-20V P-Channel Enhancement Mode MOSFET**

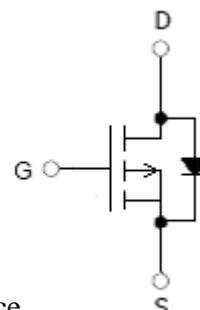
### **Features:**

- Compact and low profile SOT-23 package
- Advanced trench process technology
- High density cell design for ultra low on resistance
- Pb-free lead plating package

SOT-23



BVDSS	-20V
ID @ VGS=-10V, TA=25°C	-1.4A
RDS(on)@VGS=-4.5V, ID=-1A	102mΩ (typ)
RDS(on)@VGS=-2.5V, ID=-1A	138mΩ (typ)



G : Gate

S : Source

D : Drain

### **Ordering Information**

Device	Package	Shipping
KWP1067	SOT-23 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel

## Absolute Maximum Ratings ( $T_a=25^\circ C$ )

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	$V_{DS}$	-20	<b>V</b>
Gate-Source Voltage	$V_{GS}$	$\pm 12$	
Continuous Drain Current @ $T_A=25^\circ C$ , $V_{GS}=-4.5V$	$I_D$	-1.4	<b>A</b>
Continuous Drain Current @ $T_A=70^\circ C$ , $V_{GS}=-4.5V$		-1.1	
Pulsed Drain Current (Notes 1, 2)	$I_{DM}$	-6.0	
Maximum Power Dissipation Linear Derating Factor	$P_D$	0.4	<b>W</b>
		0.003	<b>W/<math>^\circ C</math></b>
Operating Junction and Storage Temperature Range	$T_j ; T_{stg}$	-55~+150	$^\circ C$

Note : 1. Pulse width limited by maximum junction temperature.

2. Pulse width  $\leq 100\mu s$ , duty cycle  $\leq 5\%$ .

## Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	312	$^\circ C/W$
Thermal Resistance, Junction-to-Case , max	$R_{\theta JC}$	150	

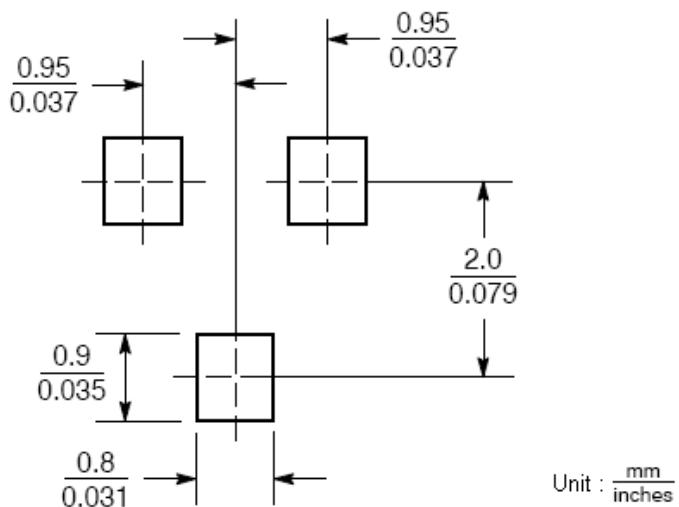
## Electrical Characteristics ( $T_j=25^\circ C$ , unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
<b>Static</b>						
$BV_{DSS}$	-20	-	-	<b>V</b>	$V_{GS}=0V, I_D=-250\mu A$	
$\Delta BV_{DSS}/\Delta T_j$	-	0.01	-	$V/^\circ C$	Reference to $25^\circ C$ , $I_D=-250\mu A$	
$V_{GS(th)}$	-0.4	-	-1.0	<b>V</b>	$V_{DS}=V_{GS}, I_D=-250\mu A$	
$I_{GSS}$	-	-	$\pm 100$	<b>nA</b>	$V_{GS}=\pm 12V, V_{DS}=0V$	
$Id_{SS}$	-	-	-1	$\mu A$	$V_{DS}=-20V, V_{GS}=0V$	
	-	-	-10		$V_{DS}=-20V, V_{GS}=0V$ ( $T_j=55^\circ C$ )	
$*R_{DS(ON)}$	-	102	145	$m\wedge$	$V_{GS}=-4.5V, I_D=-1A$	
	-	138	200		$V_{DS}=-2.5V, I_D=-1A$	
$*G_{FS}$	-	2.8	-	<b>S</b>	$V_{DS}=-10V, I_D=-1A$	
<b>Dynamic</b>						
$*Q_g$	-	4.1	-	<b>nC</b>	$V_{DS}=-16V, I_D=-1.5A, V_{GS}=-4V$	
$*Q_{gs}$	-	1.2	-			
$*Q_{gd}$	-	1.1	-			
$*t_{d(ON)}$	-	2.8	-	<b>ns</b>	$V_{DS}=-5V, I_D=-1A, V_{GS}=-5V, R_G=6\Omega$	
$*t_r$	-	17	-			
$*t_d(OFF)$	-	29.2	-			
$*t_f$	-	3.8	-			

C <sub>iss</sub>	-	350	-	pF	V <sub>DS</sub> =-5V, V <sub>GS</sub> =0V, f=1MHz
C <sub>oss</sub>	-	55	-		
C <sub>rss</sub>	-	41	-		
<b>Source-Drain Diode</b>					
*V <sub>SD</sub>	-	-0.82	-1.2	V	V <sub>GS</sub> =0V, I <sub>s</sub> =-0.63A
t <sub>rr</sub>	-	5.4	-	ns	V <sub>GS</sub> =0V, I <sub>F</sub> =-1A, dI <sub>F</sub> /dt=100A/μs
t <sub>a</sub>	-	3	-		
t <sub>b</sub>	-	2.4	-		
Q <sub>rr</sub>	-	1.7	-	nC	

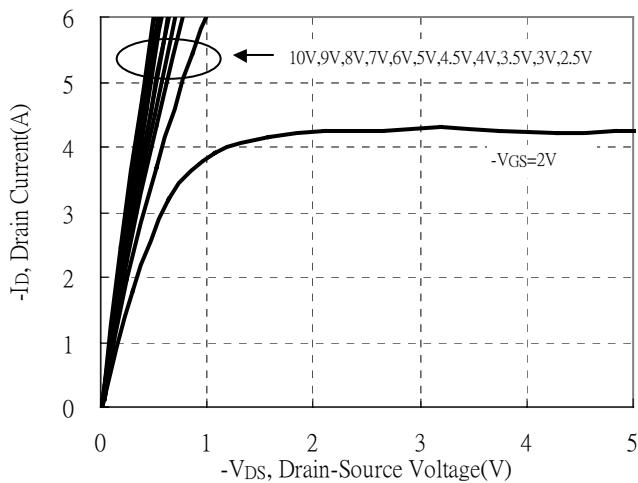
\*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

## Recommended Soldering Footprint

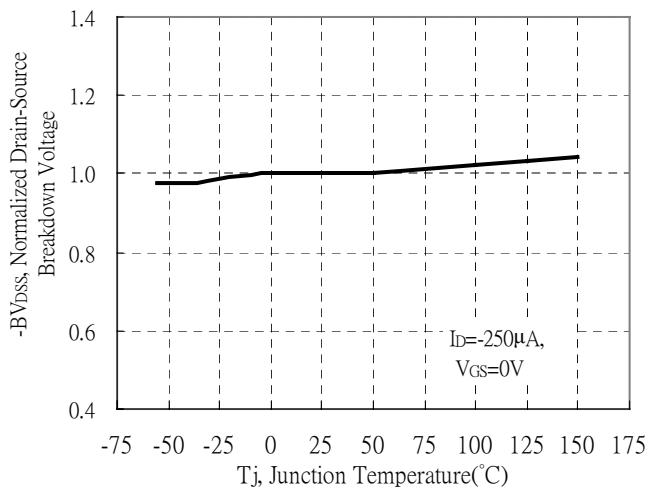


## Typical Characteristics

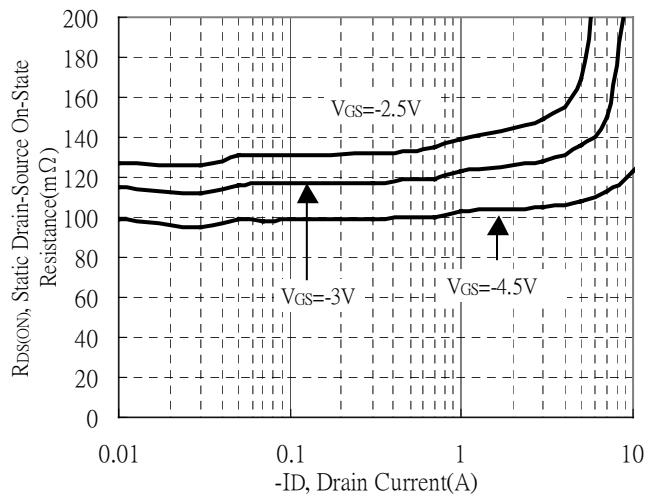
Typical Output Characteristics



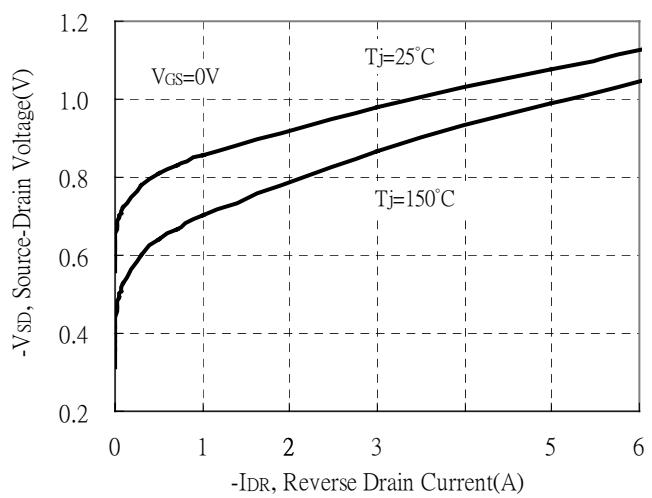
Breakdown Voltage vs Ambient Temperature



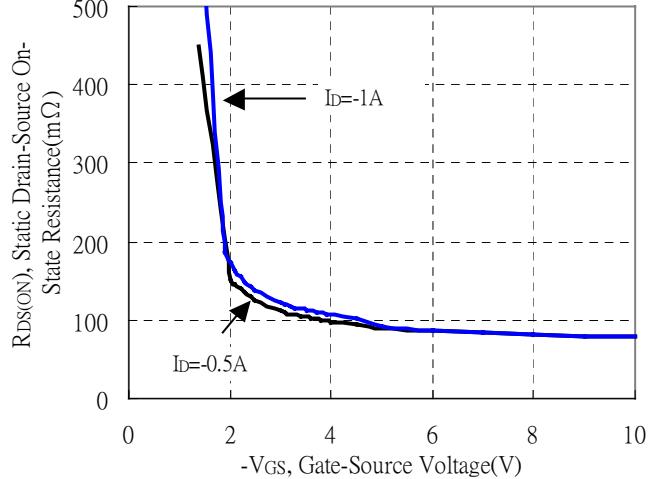
Static Drain-Source On-State resistance vs Drain Current



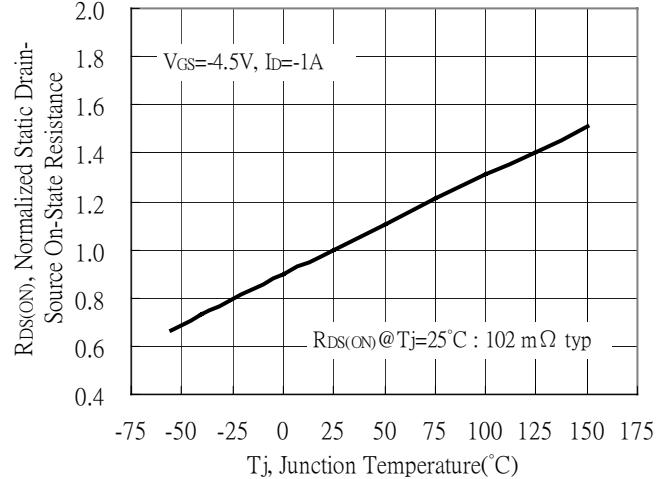
Reverse Drain Current vs Source-Drain Voltage



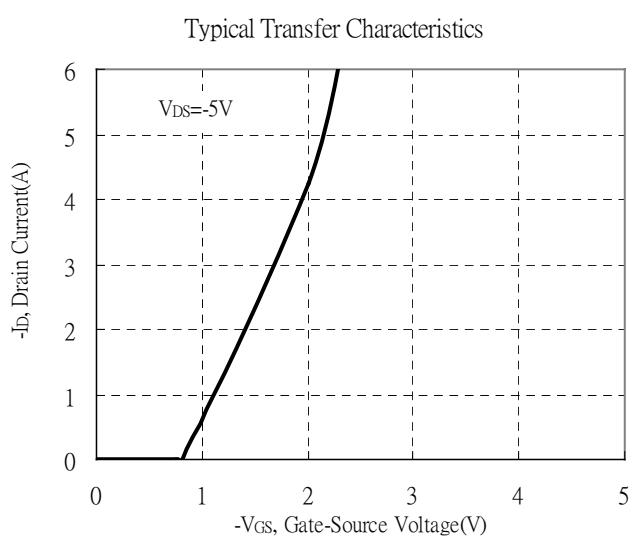
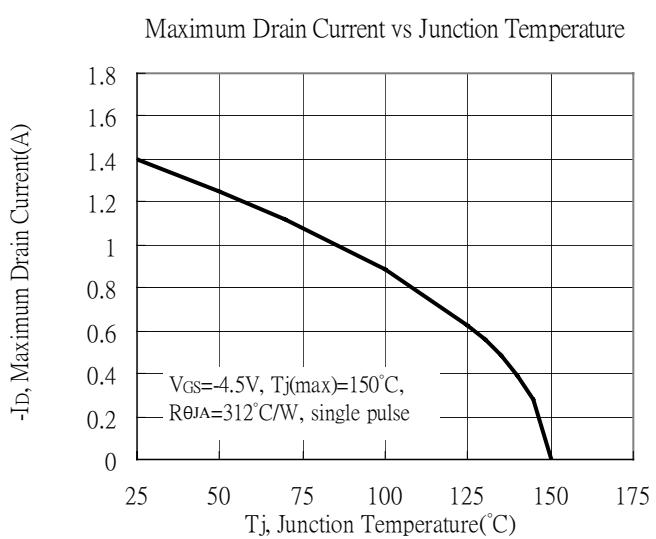
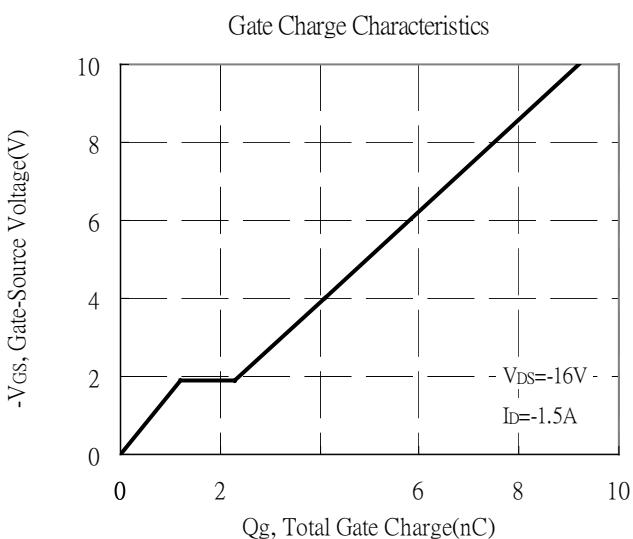
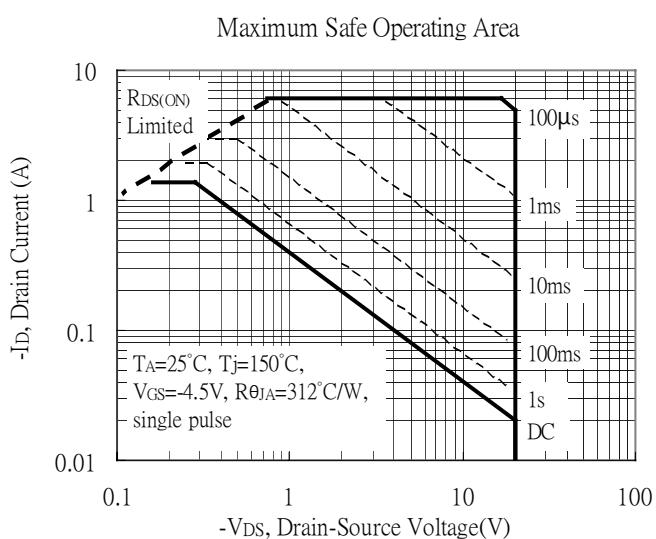
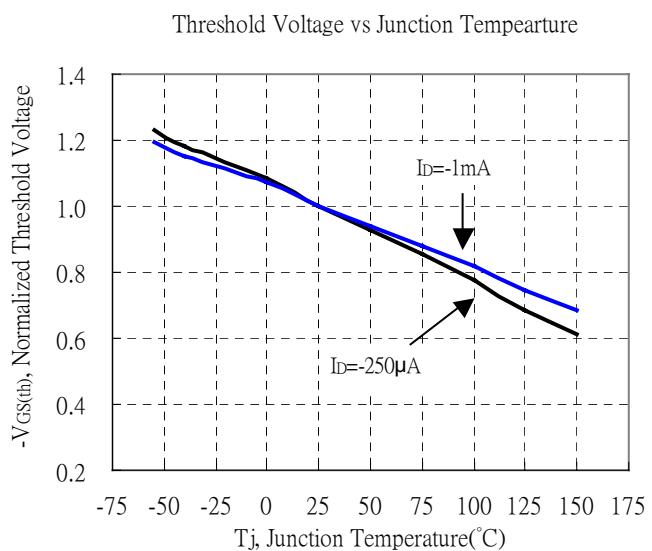
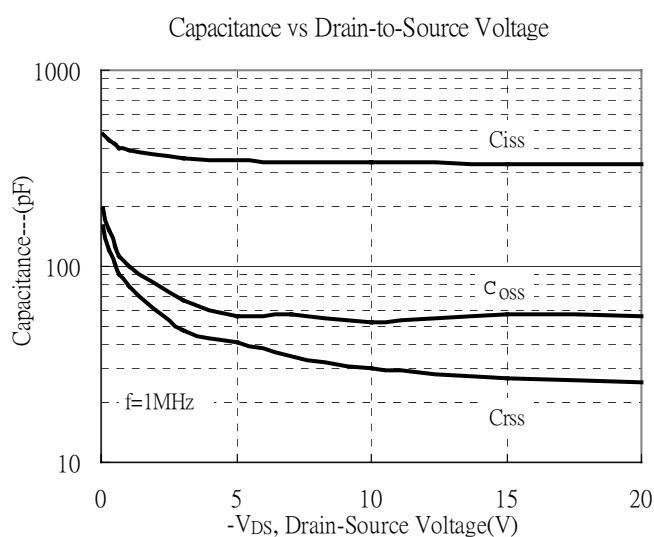
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Drain-Source On-State Resistance vs Junction Temperature

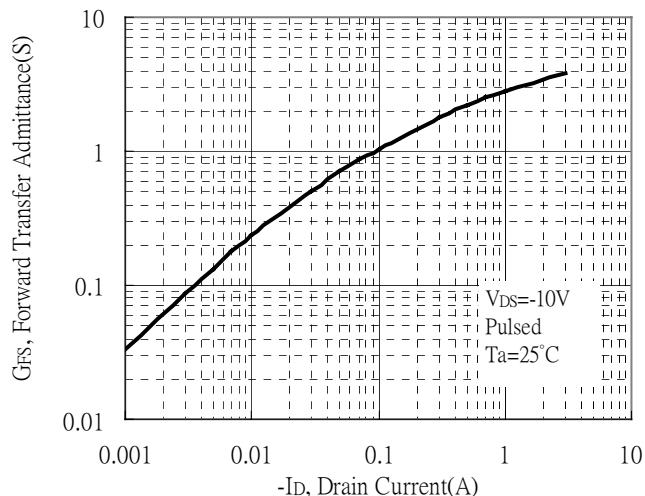


## Typical Characteristics(Cont.)

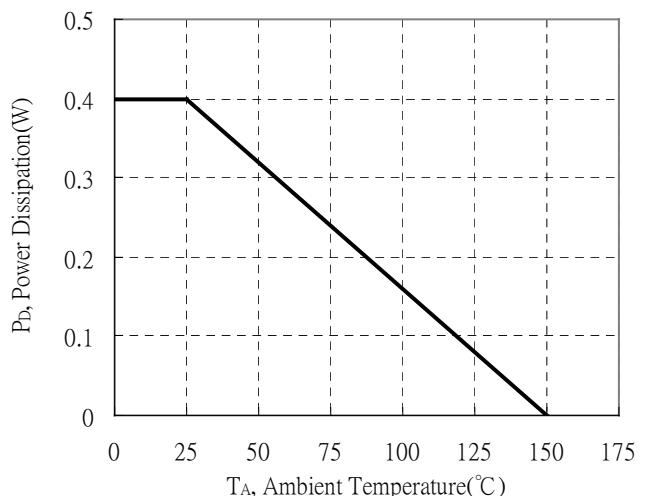


## Typical Characteristics(Cont.)

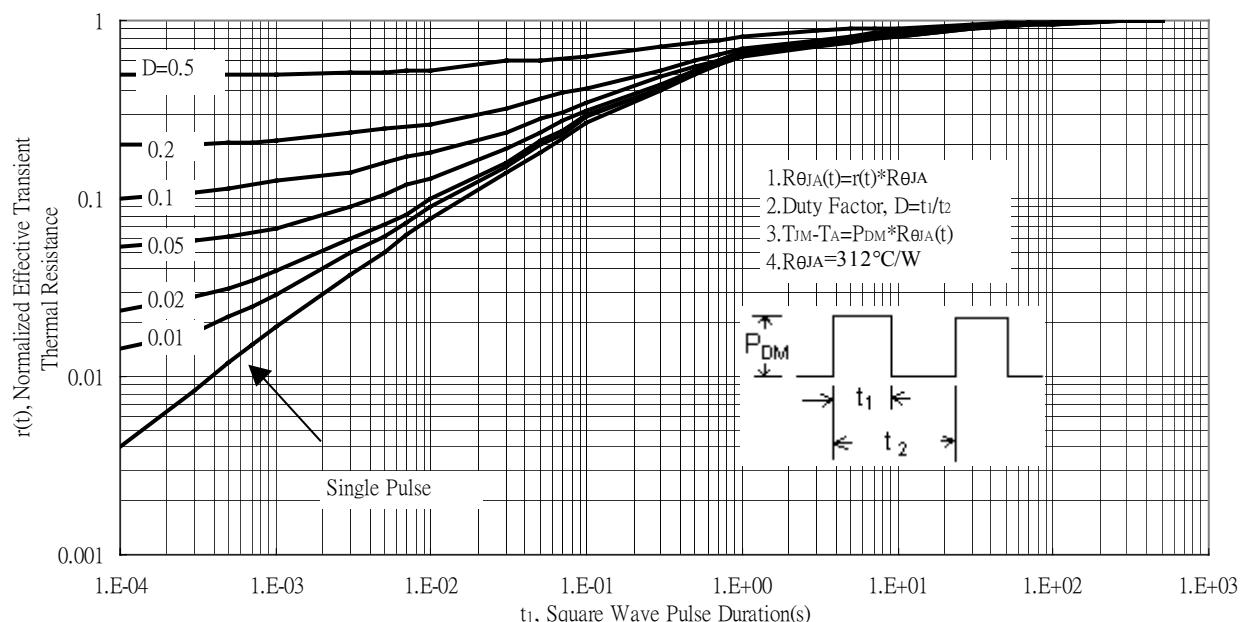
Forward Transfer Admittance vs Drain Current



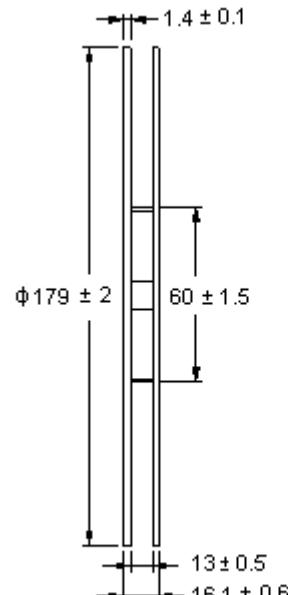
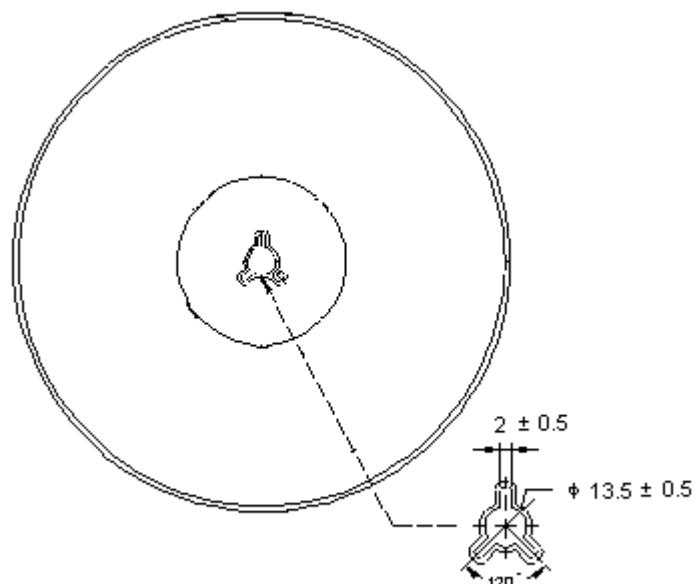
Power Derating Curve



Transient Thermal Response Curves

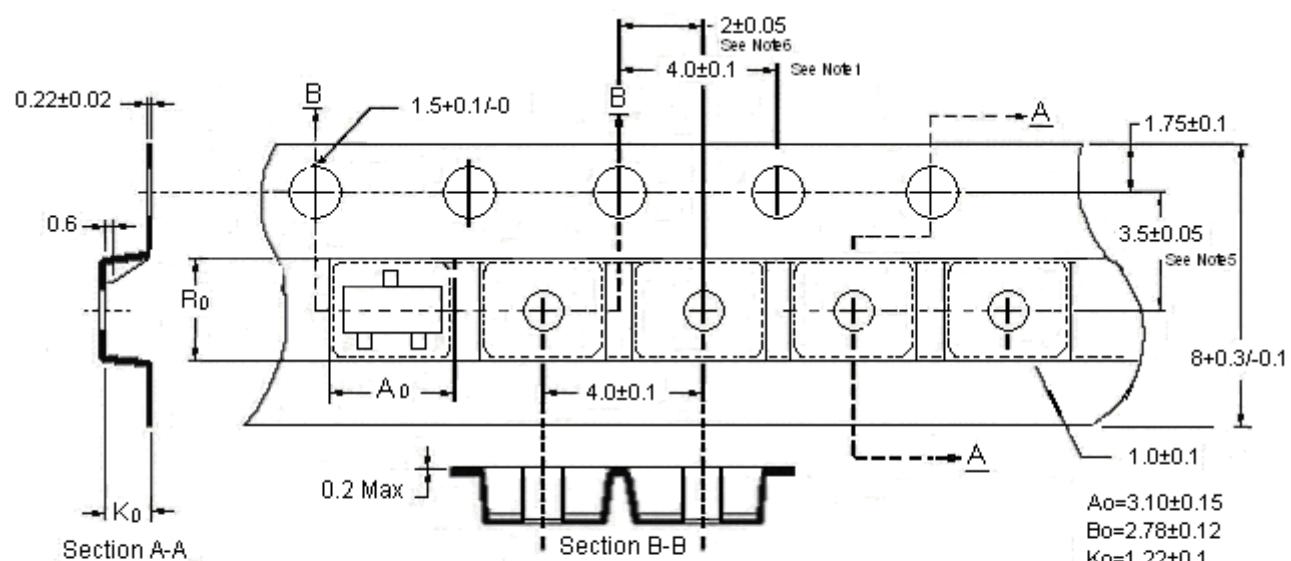


## Reel Dimension



Unit: millimeter

## Carrier Tape Dimension

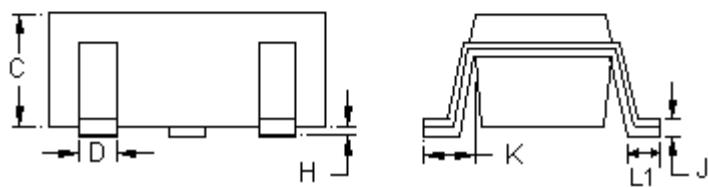
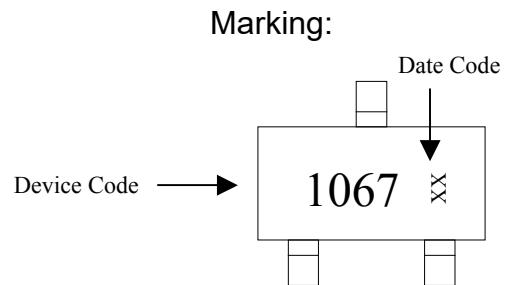
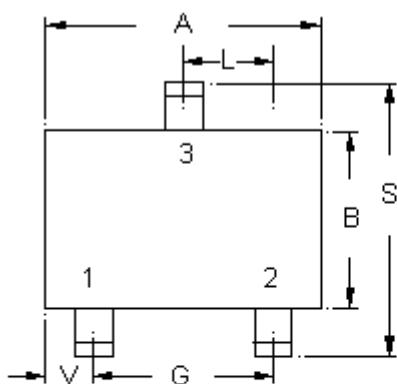


Notes:

1. 10 sprocket hole pitch cumulative tolerance  $\pm 0.2$ .
2. Camber not to exceed 1mm in 100mm.
3. Material : conductive Black Polystyrene.
4.  $A_0$  &  $B_0$  measured on a plane 0.3mm above the bottom of the pocket.
5.  $K_0$  measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

## SOT-23 Dimension



3-Lead SOT-23 Plastic Surface Mounted Package

Style: Pin 1.Gate 2.Source 3.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0032	0.0079	0.08	0.20
B	0.0472	0.0669	1.20	1.70	K	0.0118	0.0266	0.30	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1161	2.10	2.95
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0000	0.0040	0.00	0.10	L1	0.0118	0.0197	0.30	0.50